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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

-XF

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 24x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f18856t-i-ml

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Name	Function	Input Type	Output Type	Description
Vss	Vss	Power	—	Ground reference.
OUT ⁽²⁾	ADGRDA	—	CMOS/OD	ADC Guard Ring A output.
	ADGRDB	—	CMOS/OD	ADC Guard Ring B output.
	C1OUT	—	CMOS/OD	Comparator 1 output.
	C2OUT	—	CMOS/OD	Comparator 2 output.
	SDO1	—	CMOS/OD	MSSP1 SPI serial data output.
	SCK1	—	CMOS/OD	MSSP1 SPI serial clock output.
	SDO2	—	CMOS/OD	MSSP2 SPI serial data output.
	SCK2	—	CMOS/OD	MSSP2 SPI serial clock output.
	ТХ	—	CMOS/OD	EUSART Asynchronous mode transmitter data output.
	CK ⁽³⁾	—	CMOS/OD	EUSART Synchronous mode clock output.
	DT ⁽³⁾	—	CMOS/OD	EUSART Synchronous mode data output.
	DSM	—	CMOS/OD	Data Signal Modulator output.
	TMR0	—	CMOS/OD	Timer0 output.
	CCP1	—	CMOS/OD	Capture/Compare/PWM1 output (compare/PWM functions).
	CCP2	—	CMOS/OD	Capture/Compare/PWM2 output (compare/PWM functions).
	CCP3	—	CMOS/OD	Capture/Compare/PWM3 output (compare/PWM functions).
	CCP4	—	CMOS/OD	Capture/Compare/PWM4 output (compare/PWM functions).
	CCP5	—	CMOS/OD	Capture/Compare/PWM5 output (compare/PWM functions).
	PWM6OUT	—	CMOS/OD	PWM6 output.
	PWM7OUT	—	CMOS/OD	PWM7 output.
	CWG1A	—	CMOS/OD	Complementary Waveform Generator 1 output A.
	CWG1B	—	CMOS/OD	Complementary Waveform Generator 1 output B.
	CWG1C	—	CMOS/OD	Complementary Waveform Generator 1 output C.
	CWG1D	—	CMOS/OD	Complementary Waveform Generator 1 output D.
	CWG2A	—	CMOS/OD	Complementary Waveform Generator 2 output A.
	CWG2B	—	CMOS/OD	Complementary Waveform Generator 2 output B.
	CWG2C	—	CMOS/OD	Complementary Waveform Generator 2 output C.
	CWG2D	—	CMOS/OD	Complementary Waveform Generator 2 output D.
	CWG3A	—	CMOS/OD	Complementary Waveform Generator 3 output A.
	CWG3B	_	CMOS/OD	Complementary Waveform Generator 3 output B.
Legend: AN = Analog input or outp TTL = TTL compatible input	out CMOS =	 CMOS co Schmitt Tr 	mpatible input or	output OD = Open-Drain CMOS levels I^2C = Schmitt Trigger input with I^2C

TABLE 1-2: PIC16F18856 PINOUT DESCRIPTION (CONTINUED)

Note

HV = High Voltage = Crystal levels XTAL This is a PPS remappable input signal. The input function may be moved from the default location shown to one of several other PORTx 1: pins. Refer to Table 13-1 for details on which PORT pins may be used for this signal.

2: All output signals shown in this row are PPS remappable. These signals may be mapped to output onto one of several PORTx pin options as described in Table 13-3.

This is a bidirectional signal. For normal module operation, the firmware should map this signal to the same pin in both the PPS input and 3: PPS output registers.

4: These pins are configured for I²C logic levels. The SCLx/SDAx signals may be assigned to any of the RB1/RB2/RC3/RC4 pins. PPS assignments to the other pins (e.g., RA5) will operate, but input logic levels will be standard TTL/ST, as selected by the INLVL register, instead of the I²C specific or SMBus input buffer thresholds.

5.11 Determining the Cause of a Reset

Upon any Reset, multiple bits in the STATUS and PCON register are updated to indicate the cause of the Reset. Table 5-3 and Table 5-4 show the Reset conditions of these registers.

STKOVF	STKUNF	RWDT	RMCLR	RI	POR	BOR	то	PD	Condition
0	0	1	1	1	0	x	1	1	Power-on Reset
0	0	1	1	1	0	x	0	x	Illegal, TO is set on POR
0	0	1	1	1	0	x	x	0	Illegal, PD is set on POR
0	0	u	1	1	u	0	1	1	Brown-out Reset
u	u	0	u	u	u	u	0	u	WDT Reset
u	u	u	u	u	u	u	0	0	WDT Wake-up from Sleep
u	u	u	u	u	u	u	1	0	Interrupt Wake-up from Sleep
u	u	u	0	u	u	u	u	u	MCLR Reset during normal operation
u	u	u	0	u	u	u	1	0	MCLR Reset during Sleep
u	u	u	u	0	u	u	u	u	RESET Instruction Executed
1	u	u	u	u	u	u	u	u	Stack Overflow Reset (STVREN = 1)
u	1	u	u	u	u	u	u	u	Stack Underflow Reset (STVREN = 1)

TABLE 5-3: RESET STATUS BITS AND THEIR SIGNIFICANCE

TABLE 5-4: RESET CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON0 Register
Power-on Reset	0000h	1 1000	00 110x
MCLR Reset during normal operation	0000h	u uuuu	uu Ouuu
MCLR Reset during Sleep	0000h	1 Ouuu	uu Ouuu
WDT Reset	0000h	0 uuuu	uu-0 uuuu
WDT Wake-up from Sleep	PC + 1	0 Ouuu	uu-u uuuu
WDT Window Violation	0000h	0 uuuu	uu00 uuuu
Brown-out Reset	0000h	1 1000	00-1 11u0
Interrupt Wake-up from Sleep	PC + 1 ⁽¹⁾	1 Ouuu	uu-u uuuu
RESET Instruction Executed	0000h	u uuuu	uu-u u0uu
Stack Overflow Reset (STVREN = 1)	0000h	u uuuu	lu-u uuuu
Stack Underflow Reset (STVREN = 1)	0000h	u uuuu	ul-u uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and Global Enable bit (GIE) is set, the return address is pushed on the stack and PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

10.4.5 NVMREG WRITE TO PFM

Program memory is programmed using the following steps:

- 1. Load the address of the row to be programmed into NVMADRH:NVMADRL.
- 2. Load each write latch with data.
- 3. Initiate a programming operation.
- 4. Repeat steps 1 through 3 until all data is written.

Before writing to program memory, the word(s) to be written must be erased or previously unwritten. Program memory can only be erased one row at a time. No automatic erase occurs upon the initiation of the write.

Program memory can be written one or more words at a time. The maximum number of words written at one time is equal to the number of write latches. See Figure 10-4 (row writes to program memory with 32 write latches) for more details.

The write latches are aligned to the Flash row address boundary defined by the upper ten bits of NVMADRH:NVMADRL, (NVMADRH<6:0>:NVMADRL<7:5>) with the lower five bits of NVMADRL, (NVMADRL<4:0>) determining the write latch being loaded. Write operations do not cross these boundaries. At the completion of a program memory write operation, the data in the write latches is reset to contain 0x3FFF. The following steps should be completed to load the write latches and program a row of program memory. These steps are divided into two parts. First, each write latch is loaded with data from the NVMDATH:NVMDATL using the unlock sequence with LWLO = 1. When the last word to be loaded into the write latch is ready, the LWLO bit is cleared and the unlock sequence executed. This initiates the programming operation, writing all the latches into Flash program memory.

- Note: The special unlock sequence is required to load a write latch with data or initiate a Flash programming operation. If the unlock sequence is interrupted, writing to the latches or program memory will not be initiated.
- 1. Set the WREN bit of the NVMCON1 register.
- 2. Clear the NVMREGS bit of the NVMCON1 register.
- Set the LWLO bit of the NVMCON1 register. When the LWLO bit of the NVMCON1 register is '1', the write sequence will only load the write latches and will not initiate the write to Flash program memory.
- 4. Load the NVMADRH:NVMADRL register pair with the address of the location to be written.
- 5. Load the NVMDATH:NVMDATL register pair with the program memory data to be written.
- Execute the unlock sequence (Section 10.4.2 "NVM Unlock Sequence"). The write latch is now loaded.
- 7. Increment the NVMADRH:NVMADRL register pair to point to the next location.
- 8. Repeat steps 5 through 7 until all but the last write latch has been loaded.
- Clear the LWLO bit of the NVMCON1 register. When the LWLO bit of the NVMCON1 register is '0', the write sequence will initiate the write to Flash program memory.
- 10. Load the NVMDATH:NVMDATL register pair with the program memory data to be written.
- Execute the unlock sequence (Section 10.4.2 "NVM Unlock Sequence"). The entire program memory latch content is now written to Flash program memory.
- Note: The program memory write latches are reset to the blank state (0x3FFF) at the completion of every write or erase operation. As a result, it is not necessary to load all the program memory write latches. Unloaded latches will remain in the blank state.

An example of the complete write sequence is shown in Example 10-4. The initial address is loaded into the NVMADRH:NVMADRL register pair; the data is loaded using indirect addressing.

12.1.1 CURRENT-CONTROLLED DRIVE

Special precautions must be taken when enabling the current-controlled output drivers. An external resistor must be inserted in series with the load to dissipate most of the power. If an external resistor is not used then the pin circuity will dissipate all the power, thereby exceeding the maximum power specifications for the pin and the device. Determine the resistance and power rating of the external resistor such that the voltage at the pin is 0 for current sink and VDD for current source when the load is drawing the maximum expected power. For example, consider a load that is expected to vary from 1.0 to 1.5 volts. When VDD is 5V and the current is 1 mA then the combination of the external resistor and pin circuitry must make up the 3.5 to 4V difference. The external resistor should be sized to drop 3.5V at a current of 1 mA. The pin circuitry will then make up the 0 to 0.5 volt difference.

12.2 I/O Priorities

Each pin defaults to the PORT data latch after Reset. Other functions are selected with the peripheral pin select logic. See **Section 13.0** "**Peripheral Pin Select (PPS) Module**" for more information.

Analog input functions, such as ADC and comparator inputs, are not shown in the peripheral pin select lists. These inputs are active when the I/O pin is set for Analog mode using the ANSELx register. Digital output functions may continue to control the pin when it is in Analog mode.

Analog outputs, when enabled, take priority over the digital outputs and force the digital output driver to the high-impedance state.

12.3 Register Definitions: Current-Controlled Drive Configuration

REGISTER 12-1: CCDCON REGISTER

R/W-0/0	U-0	U-0	U-0	U-0	U-0	R/W-x/u	R/W-x/u
CCDEN ⁽¹⁾	—	—	—	—	—	CCDS	S<1:0>
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7	 CCDEN: Current Controlled Drive Enable bit⁽¹⁾ 1 = Current-Controlled drive is enabled for all ports. Port pins enabled for current-controlled source with the CCDPxy or current-controlled sink with the CCCNxy controls will have their current limited to that selected by the CCDS selection. 0 = Current-controlled drive disabled 					
bit 6-2	Unimplemented: Read as '0'					
bit 1-0	CCDS<1:0>: Current Controlled Drive Selection bits:					
	Current setting (mA):					
	11 = 1.0					
	10 = 2.0					
	01 = 5.0					
	00 = 10.0					

Note 1: If either CCDPxy or CCDNxy is set when CCDEN = 0, the operation of the pin is undefined.

REGISTER 12-14:	LATB: PORTB DATA LATCH REGISTER
-----------------	---------------------------------

| R/W-x/u |
|---------|---------|---------|---------|---------|---------|---------|---------|
| LATB7 | LATB6 | LATB5 | LATB4 | LATB3 | LATB2 | LATB1 | LATB0 |
| bit 7 | | | | | | | bit 0 |

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 LATB<7:0>: RB<7:0> Output Latch Value bits⁽¹⁾

Note 1: Writes to PORTB are actually written to corresponding LATB register. Reads from PORTB register is return of actual I/O pin values.

REGISTER 12-15: ANSELB: PORTB ANALOG SELECT REGISTER

| R/W-1/1 |
|---------|---------|---------|---------|---------|---------|---------|---------|
| ANSB7 | ANSB6 | ANSB5 | ANSB4 | ANSB3 | ANSB2 | ANSB1 | ANSB0 |
| bit 7 | | | | | | | bit 0 |

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **ANSB<7:0>**: Analog Select between Analog or Digital Function on pins RB<7:0>, respectively

1 = Analog input. Pin is assigned as analog input⁽¹⁾. Digital input buffer disabled.

0 = Digital I/O. Pin is assigned to port or digital special function.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.



INTERRUPT-ON-CHANGE BLOCK DIAGRAM (PORTA EXAMPLE) FIGURE 15-1:

REGISTER 19-2: PWMxDCH: PWM DUTY CYCLE HIGH BITS

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
			PWMx	DC<9:2>			
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable b	it	U = Unimplen	nented bit, read	l as '0'	
u = Bit is unch	nanged	x = Bit is unkno	own	-n/n = Value a	at POR and BO	R/Value at all o	other Resets
'1' = Bit is set		'0' = Bit is clea	red				

bit 7-0 PWMxDC<9:2>: PWM Duty Cycle Most Significant bits These bits are the MSbs of the PWM duty cycle. The two LSbs are found in PWMxDCL Register.

REGISTER 19-3: PWMxDCL: PWM DUTY CYCLE LOW BITS

R/W-x/u	R/W-x/u	U-0	U-0	U-0	U-0	U-0	U-0
PWMxD	C<1:0>	—	—	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 PWMxDC<1:0>: PWM Duty Cycle Least Significant bits

These bits are the LSbs of the PWM duty cycle. The MSbs are found in PWMxDCH Register.

bit 5-0 Unimplemented: Read as '0'

TABLE 23-1: ADC CLOCK PERIOD (TAD) Vs. DEVICE OPERATING FREQUENCIES

ADC Clock Period (TAD)		Device Frequency (Fosc)							
ADC Clock Source	ADCCS<5:0>	32 MHz	20 MHz	16 MHz	8 MHz	4 MHz	1 MHz		
Fosc/2	000000	62.5ns ⁽²⁾	100 ns ⁽²⁾	125 ns ⁽²⁾	250 ns ⁽²⁾	500 ns ⁽²⁾	2.0 μs		
Fosc/4	000001	125 ns ⁽²⁾	200 ns ⁽²⁾	250 ns ⁽²⁾	500 ns ⁽²⁾	1.0 μs	4.0 μs		
Fosc/6	000010	187.5 ns ⁽²⁾	300 ns ⁽²⁾	375 ns ⁽²⁾	750 ns ⁽²⁾	1.5 μs	6.0 μs		
Fosc/8	000011	250 μs ⁽²⁾	400 ns ⁽²⁾	500 μs ⁽²⁾	1.0 μs	2.0 μs	8.0 μs ⁽³⁾		
Fosc/16	000111	500 ns ⁽²⁾	800 ns ⁽²⁾	1.0 μs	2.0 μs	4.0 μs	16.0 μs ⁽²⁾		
Fosc/128	111111	4.0 μs	6.4 μs	8.0 μs	16.0 μs ⁽³⁾	32.0 μs ⁽²⁾	128.0 μs ⁽²⁾		
FRC	ADCS(ADCON0 <4>)=1	1.0-6.0 μs ⁽¹⁾							

Legend: Shaded cells are outside of recommended range.

Note 1: See TAD parameter for FRC source typical TAD value.

- **2:** These values violate the required TAD time.
- **3:** Outside the recommended TAD time.
- 4: The ADC clock period (TAD) and total ADC conversion time can be minimized when the ADC clock is derived from the system clock FOSC. However, the FRC oscillator source must be used when conversions are to be performed with the device in Sleep mode.

FIGURE 23-2: ANALOG-TO-DIGITAL CONVERSION TAD CYCLES (ADSC = 0)



23.3 ADC Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 23-4. The source impedance (Rs) and the internal sampling switch (Rss) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (Rss) impedance varies over the device voltage (VDD), refer to Figure 23-4. The maximum recommended impedance for analog sources is 10 k Ω . As the

source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an ADC acquisition must be completed before the conversion can be started. To calculate the minimum acquisition time, Equation 23-1 may be used. This equation assumes that 1/2 LSb error is used (1,024 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 23-1: ACQUISITION TIME EXAMPLE

Assumptions: Temperature =
$$50^{\circ}C$$
 and external impedance of $10k\Omega 5.0V$ VDD
 $TACQ = Amplifier Settling Time + Hold Capacitor Charging Time + Temperature Coefficient$
 $= TAMP + TC + TCOFF$
 $= 2\mu s + TC + [(Temperature - 25^{\circ}C)(0.05\mu s/^{\circ}C)]$

The value for TC can be approximated with the following equations:

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD} ; [1] V_{CHOLD} charged to within 1/2 lsb$$

$$V_{APPLIED}\left(1 - e^{\frac{-TC}{RC}}\right) = V_{CHOLD} ; [2] V_{CHOLD} charge response to V_{APPLIED} V_{APPLIED}\left(1 - e^{\frac{-TC}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) ; combining [1] and [2]$$

Note: Where n = number of bits of the ADC.

Solving for TC:

ł

$$Tc = -C_{HOLD}(RIC + RSS + RS) \ln(1/2047)$$

= -10pF(1k\Omega + 7k\Omega + 10k\Omega) \ln(0.0004885)
= 1.37\mus

Therefore:

$$TACQ = 2\mu s + 892ns + [(50^{\circ}C - 25^{\circ}C)(0.05\mu s/^{\circ}C)]$$

= 4.62\mu s

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

- 2: The charge holding capacitor (CHOLD) is not discharged after each conversion.
- **3:** The maximum recommended impedance for analog sources is $10 \text{ k}\Omega$. This is required to meet the pin leakage specification.

REGISTER 23-4: ADCON3: ADC THRESHOLD REGISTER

U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W/HC-0	R/W-0/0	R/W-0/0	R/W-0/0
—	/	ADCALC<2:0>		ADSOI		ADTMD<2:0>	
bit 7							bit 0

Legend:

Legena.		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	HC = Bit is cleared by hardware

bit 7 Unimplemented: Read as '0'

bit 6-4 ADCAL<2:0>: ADC Error Calculation Mode Select bits

	Action During	1st Precharge Stage	
ADCALC	ADDSEN = 0 Single-Sample Mode	ADDSEN = 1 CVD Double-Sample Mode ⁽¹⁾	Application
111	Reserved	Reserved	Reserved
110	Reserved	Reserved	Reserved
101	ADFLTR-ADSTPT	ADFLTR-ADSTPT	Average/filtered value vs. setpoint
100	ADPREV-ADFLTR	ADPREV-ADFLTR	First derivative of filtered value ⁽³⁾ (negative)
011	Reserved	Reserved	Reserved
010	ADRES-ADFLTR	(ADRES-ADPREV)-ADFLTR	Actual result vs. averaged/filtered value
001	ADRES-ADSTPT	(ADRES-ADPREV)-ADSTPT	Actual result vs.setpoint
000	ADRES-ADPREV	ADRES-ADPREV	First derivative of single measurement ⁽²⁾
			Actual CVD result in CVD mode ⁽²⁾

bit 3 ADSOI: ADC Stop-on-Interrupt bit

If ADCONT = 1:

1 = ADGO is cleared when the threshold conditions are met, otherwise the conversion is retriggered
 0 = ADGO is not cleared by hardware, must be cleared by software to stop retriggers
 If ADCONT = 0 bit is ignored.

bit 2-0 ADTMD<2:0>: Threshold Interrupt Mode Select bits

- 111 = Always set ADTIF at end of calculation
- 110 = Set ADTIF if ADERR>ADUTH
- 101 = Set ADTIF if ADERR≤ADUTH
- 100 = Set ADTIF if ADERR<ADLTH or ADERR>ADUTH
- 011 = Set ADTIF if ADERR>ADLTH and ADERR<ADUTH
- 010 = Set ADTIF if ADERR≥ADLTH
- 001 = Set ADTIF if ADERR<ADLTH
- 000 = ADTIF is disabled

Note 1: When ADPSIS = 0, the value of (ADRES-ADPREV) is the value of (S2-S1) from Table 23-3.

- **2:** When ADPSIS = 0
- 3: When ADPSIS = 1.

REGISTER 26-5: MDCARL: MODULATION LOW CARRIER CONTROL REGISTER	REGISTER 26-5:	MDCARL: MODULATION LOW CARRIER CONTROL REGISTER
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U-0	U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	
	_	_	_	MDCLS<3:0>(1)				
bit 7	•	•					bit 0	
Legend:								
R = Readable	e bit	W = Writable	bit	U = Unimpler	nented bit, read	l as '0'		
u = Bit is uncl	hanged	x = Bit is unki	nown	-n/n = Value a	at POR and BO	R/Value at all c	other Resets	
'1' = Bit is set		'0' = Bit is cle	ared					
bit 7-4	Unimplemen	ted: Read as '	0'					
bit 3-0	MDCLS<3:0	MDCI S<3:0> Modulator Data High Carrier Selection bits ⁽¹⁾						
	1111 = LC4	out			-			
	1110 = LC3	out						
	1101 = LC2	_ out						
	1100 = LC1	out						
	1011 = NCC	Doutput						
	1010 = PWI	M7 out						
	1001 = PWI	M6 out						
	1000 = CCF	P5 output (PWN	/ Output mode	e only)				
	0111 = CCF	P4 output (PWN	/ Output mode	e only)				
	0110 = CCF	P3 output (PWN	/ Output mode	e only)				
	0101 = CCF	P2 output (PWN	/ Output mode	e only)				
	0100 = CCF	P1 output (PWN	/ Output mode	e only)				
	0011 = Refe	erence clock m	odule signal (CLKR)				
	0010 = HFH	NTOSC						
	0001 = Fos	С						
	0000 = Pin	selected by MD	DCARLPPS					

Note 1: Narrowed carrier pulse widths or spurs may occur in the signal stream if the carrier is not synchronized.



R/W/HC-0/0	R/W/HC-0/0	R/W/HC-0/0	U-0	U-0	R-0/0	R-0/0	R-0/0
CPRUP	CPWUP	RST	_		TS	WS	AS
bit 7							bit 0
Legend:							
HC = Bit is clea	ared by hardwa	are		HS = Bit is se	et by hardware		
R = Readable	bit	W = Writable	bit	U = Unimpler	nented bit, read	d as '0'	
u = Bit is unch	anged	x = Bit is unkr	nown	-n/n = Value a	at POR and BC	R/Value at all	other Resets
'1' = Bit is set		'0' = Bit is clea	ared	q = Value dep	pends on condi	tion	
bit 7 CPRUP: SMT Manual Period Buffer Update bit							
	0 = SMTxPR	k registers upd	ate is complete	;			
bit 6 CPWUP: SMT Manual Pulse Width Buffer 1 = Request update to SMTxCPW register 0 = SMTxCPW registers update is comple				Update bit s æ			
bit 5	RST: SMT Ma 1 = Request F 0 = SMTxTM	anual Timer Re Reset to SMTx R registers upc	set bit TMR registers late is complet	e			
bit 4-3	Unimplemen	ted: Read as '	0'				
bit 2	bit 2 TS : SMT GO Value Status bit 1 = SMT timer is incrementing 0 = SMT timer is not incrementing						
bit 1 WS: SMTxWIN Value Status bit 1 = SMT window is open 0 = SMT window is closed							
bit 0	AS: SMT_sig 1 = SMT acqu 0 = SMT acqu	nal Value Statu uisition is in pro uisition is not ir	s bit ogress o progress				

REGISTER 32-3: SMTxSTAT: SMT STATUS REGISTER

REGISTER 32-7: SMTxTMRL: SMT TIMER REGISTER – LOW BYTE

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
			SMTxTN	/IR<7:0>			
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable I	bit	U = Unimplen	nented bit, read	d as '0'	
u = Bit is unch	anged	x = Bit is unkn	iown	-n/n = Value a	at POR and BO	R/Value at all o	other Resets
'1' = Bit is set		'0' = Bit is clea	ared				

bit 7-0 SMTxTMR<7:0>: Significant bits of the SMT Counter – Low Byte

REGISTER 32-8: SMTxTMRH: SMT TIMER REGISTER – HIGH BYTE

| R/W-0/0 |
|---------|---------|---------|---------|---------|---------|---------|---------|
| | | | SMTxTM | R<15:8> | | | |
| bit 7 | | | | | | | bit 0 |

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 SMTxTMR<15:8>: Significant bits of the SMT Counter – High Byte

REGISTER 32-9: SMTxTMRU: SMT TIMER REGISTER – UPPER BYTE

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	
SMTxTMR<23:16>								
bit 7 bit 0								

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 SMTxTMR<23:16>: Significant bits of the SMT Counter – Upper Byte

REGISTER 32-16: SMTxPRL: SMT PERIOD REGISTER – LOW BYTE

R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	
SMTxPR<7:0>								
bit 7							bit 0	
Legend:								
R = Readable	bit	W = Writable I	oit	U = Unimpler	mented bit, read	d as '0'		
u = Bit is uncha	anged	x = Bit is unkn	own	-n/n = Value a	at POR and BC	R/Value at all	other Resets	
'1' = Bit is set		'0' = Bit is clea	ared					

bit 7-0 SMTxPR<7:0>: Significant bits of the SMT Timer Value for Period Match – Low Byte

REGISTER 32-17: SMTxPRH: SMT PERIOD REGISTER – HIGH BYTE

R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1
SMTxPR<15:8>							
bit 7 bit (

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 SMTxPR<15:8>: Significant bits of the SMT Timer Value for Period Match – High Byte

REGISTER 32-18: SMTxPRU: SMT PERIOD REGISTER – UPPER BYTE

R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1	R/W-x/1
SMTxPR<23:16>							
bit 7 bit 0							

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 SMTxPR<23:16>: Significant bits of the SMT Timer Value for Period Match – Upper Byte

R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
CLKREN	_	_	CLKRE)C<1:0>	(CLKRDIV<2:0>	
bit 7							bit 0
Legend:							
R = Readable bitW = Writable bitU = Unimplemented bit, read as '0'					l as '0'		
u = Bit is unch	anged	x = Bit is unkr	iown	-n/n = Value a	at POR and BO	R/Value at all o	other Resets
'1' = Bit is set		'0' = Bit is clea	ared				
bit 7	CLKREN: Re	ference Clock	Module Enable	e bit			
	1 = Referen	ce Clock modu	le enabled				
	0 = Referen	ce Clock modu	le is disabled				
bit 6-5	Unimplement	ted: Read as '	כ'				
bit 4-3	CLKRDC<1:0	>: Reference (Clock Duty Cy	cle bits ⁽¹⁾			
	11 = Clock ou	Itputs duty cycl	e of 75%				
	10 = Clock out	Itputs duty cycl	e of 50%				
	01 = Clock ou	itputs duty cycl	e of 25%				
h it 0 0				h:4-			
DIT 2-0		U>: Reference		DIIS			
	111 = Input cl	lock divided by lock divided by	128				
	101 = Input cl	lock divided by	32				
	100 = Input cl	lock divided by	16				
	011 = Input cl	lock divided by	8				
	010 = Input cl	lock divided by	4				
	001 = Input cl	lock divided by	2				
	000 = Input cl	IOCK					

REGISTER 34-1: CLKRCON: REFERENCE CLOCK CONTROL REGISTER

Note 1: Bits are valid for Reference Clock divider values of two or larger, the base clock cannot be further divided.

36.0 INSTRUCTION SET SUMMARY

Each instruction is a 14-bit word containing the operation code (opcode) and all required operands. The opcodes are broken into three broad categories.

- Byte Oriented
- · Bit Oriented
- Literal and Control

The literal and control category contains the most varied instruction word format.

Table 36-4 lists the instructions recognized by the MPASM $^{\rm TM}$ assembler.

All instructions are executed within a single instruction cycle, with the following exceptions, which may take two or three cycles:

- Subroutine takes two cycles (CALL, CALLW)
- Returns from interrupts or subroutines take two cycles (RETURN, RETLW, RETFIE)
- Program branching takes two cycles (GOTO, BRA, BRW, BTFSS, BTFSC, DECFSZ, INCSFZ)
- One additional instruction cycle will be used when any instruction references an indirect file register and the file select register is pointing to program memory.

One instruction cycle consists of 4 oscillator cycles; for an oscillator frequency of 4 MHz, this gives a nominal instruction execution rate of 1 MHz.

All instruction examples use the format '0xhh' to represent a hexadecimal number, where 'h' signifies a hexadecimal digit.

36.1 Read-Modify-Write Operations

Any instruction that specifies a file register as part of the instruction performs a Read-Modify-Write (R-M-W) operation. The register is read, the data is modified, and the result is stored according to either the instruction, or the destination designator 'd'. A read operation is performed on a register even if the instruction writes to that register.

TABLE 36-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1). The assembler will generate code with x = 0 . It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1.
n	FSR or INDF number. (0-1)
mm	Prepost increment-decrement mode selection

TABLE 36-2: ABBREVIATION DESCRIPTIONS

Field	Description
PC	Program Counter
TO	Time-Out bit
С	Carry bit
DC	Digit Carry bit
Z	Zero bit
PD	Power-Down bit

Note: Unless otherwise noted, VIN = 5V, Fosc = 300 kHz, CIN = 0.1 μ F, TA = 25°C.



FIGURE 38-55: Comparator Offset, NP Mode (CxSP = 1), VDD = 5.5V, Typical Measured Values from -40°C to 125°C, PIC16F18856/76 Only.



FIGURE 38-56: Comparator Response Time Over Voltage, NP Mode (CxSP = 1), Typical Measured Values, PIC16LF18856/76 Only.



FIGURE 38-57: Comparator Response Time Over Voltage, NP Mode (CxSP = 1), Typical Measured Values, PIC16F18856/76 Only.



FIGURE 38-58: Typical DAC DNL Error, VDD = 3.0V, VREF = External 3V.



FIGURE 38-59: Typical DAC INL Error, VDD = 3.0V, VREF = External 3V.



FIGURE 38-60: Typical DAC DNL Error, VDD = 5.0V, VREF = External 5V, PIC16F18856/76 Only.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





	MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX
Number of Pins	Ν		28	
Pitch	е		1.27 BSC	
Overall Height	Α	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E 10.30 BSC			
Molded Package Width	E1	7.50 BSC		
Overall Length	D	17.90 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	С	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic
- 3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M BSC: Basic Dimension. Theoretically exact value shown without tolerances. REF: Reference Dimension, usually without tolerance, for information purposes only.
- 5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	Е	1.27 BSC		
Contact Pad Spacing	С		9.40	
Contact Pad Width (X28)	Х			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A